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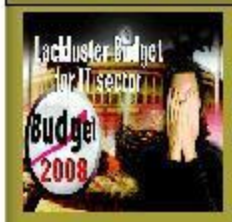

The budget is not tuned well to create a cheerful symphony as far as the Indian IT industry is concerned.

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Kaustuv Ray, Chairman

Apacer launches Aeolus DDR3-1800MHz/1600MHz memory module

By NCN News Network

Apacer Technology has announced the launch of its Aeolus series of DDR3-1800MHz/1600MHz overclocking memory modules. These modules use DDR3 / 1Gbit / 128Mx8 die manufactured using Micron Technology's most advanced production process technology. The dual-channel architecture provides maximum bandwidth of 28.8GB (1800MHz) / 25.6GB (1600MHz) with low-latency CL7-7-7-20 timing, giving the Apacer Aeolus DDR3 memory modules outstanding performance in the 1800MHz / 1600MHz product category.

Besides providing ultra-high speed and ultra-low latency, the Apacer Aeolus memory modules also use a unique, patented active heat spreader design that makes it possible to reduce the temperature by as much as 20°C. This highly effective solution to the problem of heat dissipation for DDR3 overclocking memory modules improves both overclocking performance and memory stability.

Grace Lo, Senior Director of Apacer's DRAM Division explains that the operating frequency for DDR3 overclocking memory modules has risen to 1600MHz, 1800MHz and even 2000MHz. If memory die is operating for an extended period in a high-frequency, high-voltage environment, the memory chip will inevitably reach a high temperature. This heat must be dissipated as rapidly as possible to ensure that the stability of the memory module is not compromised; extended periods of high-temperature operation could affect the module's lifespan. Most of the overclocking memory products on the market today ignore the importance of the heat spreader to overclocking memory performance; the vast majority of commercial overclocking memory module products continue to use traditional, standard-sized heatsink designs that reduce the temperature by only around 3 to 5 degrees. Heatsinks of this type are simply unable to cope with the high temperatures created by DDR3 overclocking. As a result, many overclocking enthusiasts complain that memory module heat sinks are completely useless.

Apacer's new DDR3-1800MHz/1600MHz memory module provides 2GB of memory capacity in a dual-channel (1GB'2) package, and supports Intel's latest XMP (Extreme Memory Profiles). When used with a motherboard that supports Intel XMP, the chipset will automatically read the memory module's SPD (Serial Presence Detect) and will then automatically perform overclocking, enabling the user to experience all the excitement and power that overclocking has to offer.

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